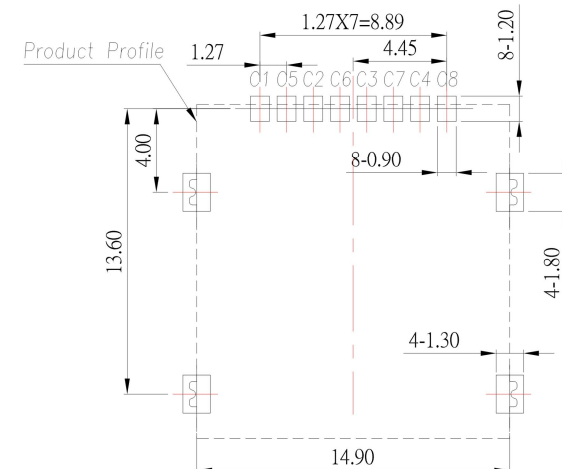
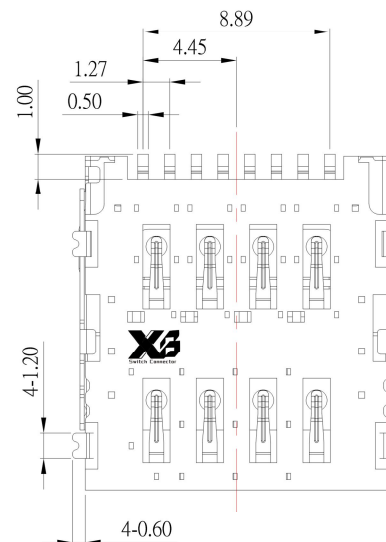
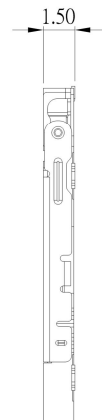
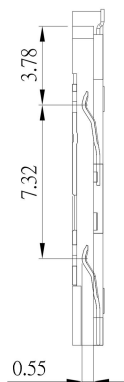


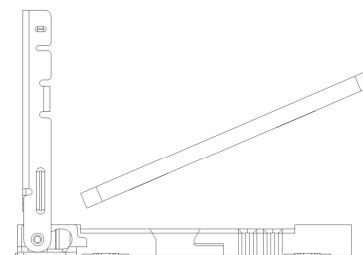


0.10 MAX

+0.05 (U.S.L.)
(HOUSING BOTTOM)

-0.15 (L.S.L.)
SMT SIDE

COPLANARITY



STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH

- 1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

TOLERANCE UNLESS OTHERWISE STATED :	Up to 5	± 0.2
	Above 5 ~ 15	± 0.3
	Above 15 ~ 30	± 0.4
	Above 30 ~ 50	± 0.5
	Angle	± 0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE
Jack Lu	03/22/18
CHECKED BY:	DATE
Jacky Chen	03/22/18
APPROVED BY:	DATE
Tony Kao	03/22/18

DATE _____

03/22/18

DATE _____

03/22/18

MAT'L

FINISH

SCALE

1 : 1

TITLE

MODLE

DWG NC

CONNECTOR

MICRO SIM 8PIN H1.5 掀蓋

MSIM-08H150-S267

	SIZE
	A4
	VER
	A0